



Material Content Data Sheet



Halogen-Free

Sales Product Name	IR3887MTRPBF	Issued	08. April 2022
MA#	MA005583861		
Package	PG-IQFN-29-1	Weight*	70.08 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.200	0.28	0.28	2847	2847
chip_2	inorganic material	silicon	7440-21-3	0.690	0.98	0.98	9848	9848
chip_3	inorganic material	silicon	7440-21-3	1.552	2.21	2.21	22142	22142
leadframe	inorganic material	phosphorus	7723-14-0	0.007	0.01		98	
	non noble metal	zinc	7440-66-6	0.027	0.04		392	
	non noble metal	iron	7439-89-6	0.549	0.78		7837	
	non noble metal	copper	7440-50-8	22.301	31.83	32.66	318207	326534
wire	noble metal	gold	7440-57-5	0.236	0.34	0.34	3369	3369
encapsulation	organic material	carbon black	1333-86-4	0.239	0.34		3410	
	non noble metal	metal hydroxide	-	0.478	0.68		6821	
	inorganic material	amorphous silica	7631-86-9	1.673	2.39		23872	
	plastics	epoxy resin	-	2.390	3.41		34103	
	inorganic material	silicon dioxide	60676-86-0	19.120	27.28	34.10	272823	341029
leadfinish	non noble metal	tin	7440-31-5	0.895	1.28	1.28	12773	12773
plating	noble metal	silver	7440-22-4	0.527	0.75	0.75	7522	7522
solder	noble metal	silver	7440-22-4	0.087	0.12		1246	
	non noble metal	tin	7440-31-5	0.175	0.25		2492	
	non noble metal	lead	7439-92-1	3.231	4.61	4.98	46096	49834
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.01		67	
	non noble metal	zinc	7440-66-6	0.019	0.03		269	
	non noble metal	iron	7439-89-6	0.377	0.54		5378	
	non noble metal	copper	7440-50-8	15.305	21.84	22.42	218388	224102
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com